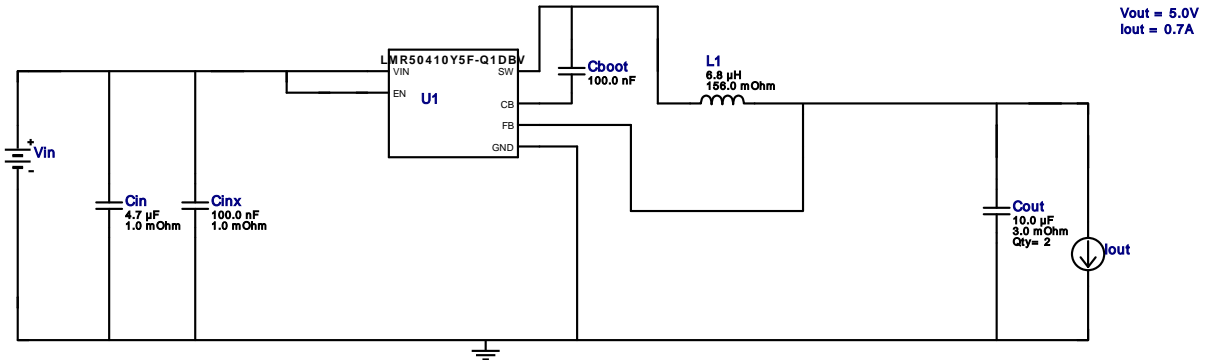


WEBENCH® Design Report

Design : 18 LMR50410Y5FQDBVRQ1
LMR50410Y5FQDBVRQ1 7V-36V to 5.00V @ 0.7A

VinMin = 7.0V
VinMax = 36.0V
Vout = 5.0V
Iout = 0.7A

Device = LMR50410Y5FQDBVRQ1
Topology = Buck
Created = 2023-08-18 06:29:39.527
BOM Cost = NA
BOM Count = 7
Total Pd = 1.03W



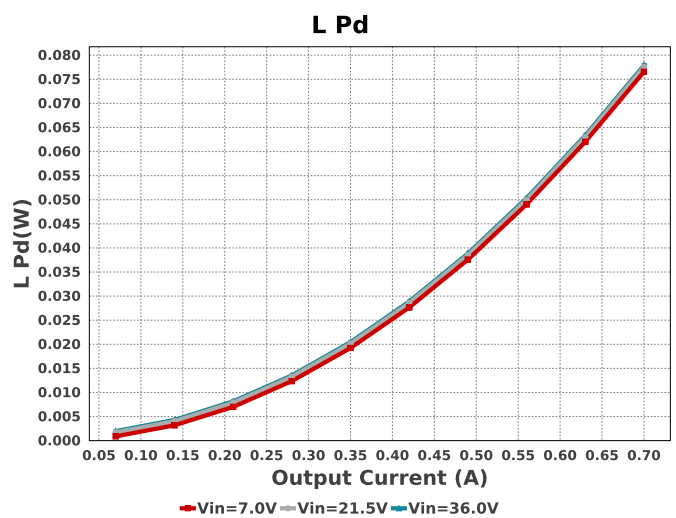
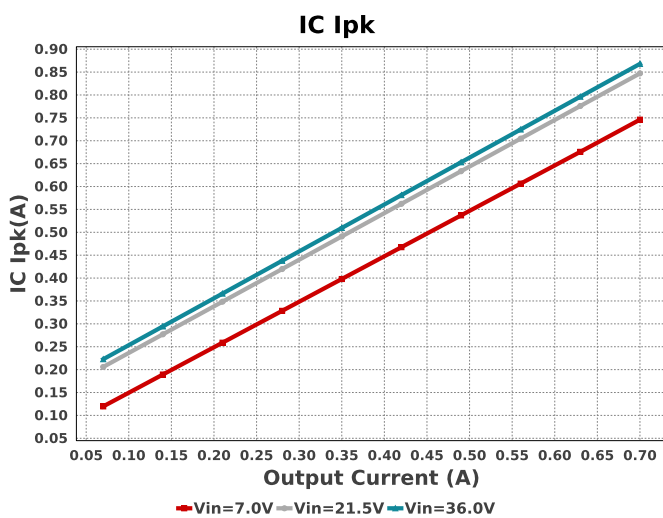
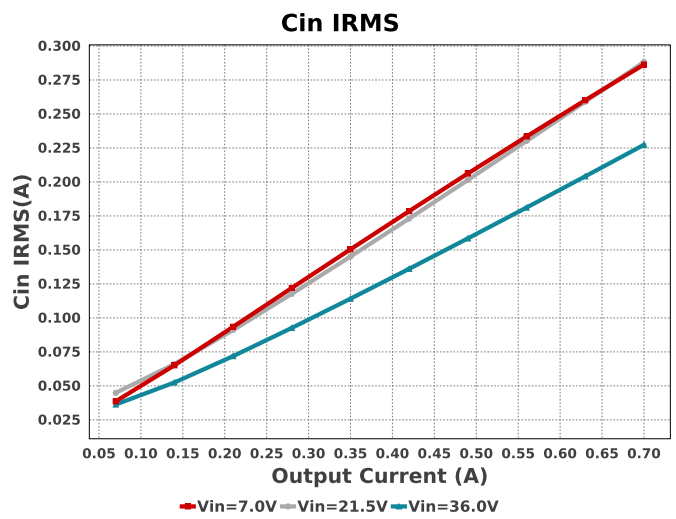
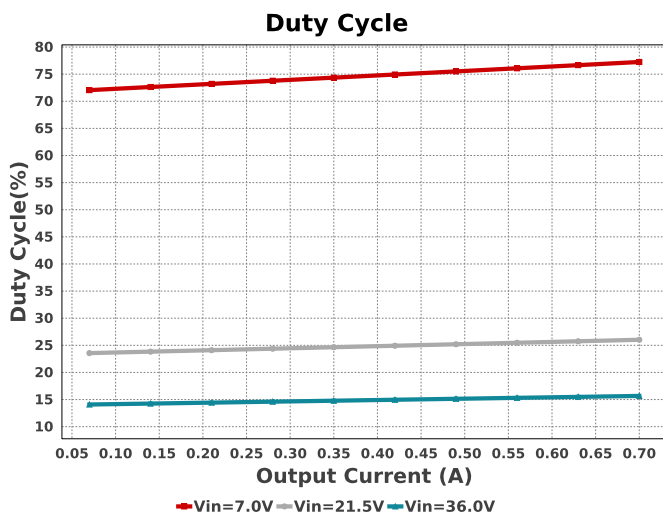
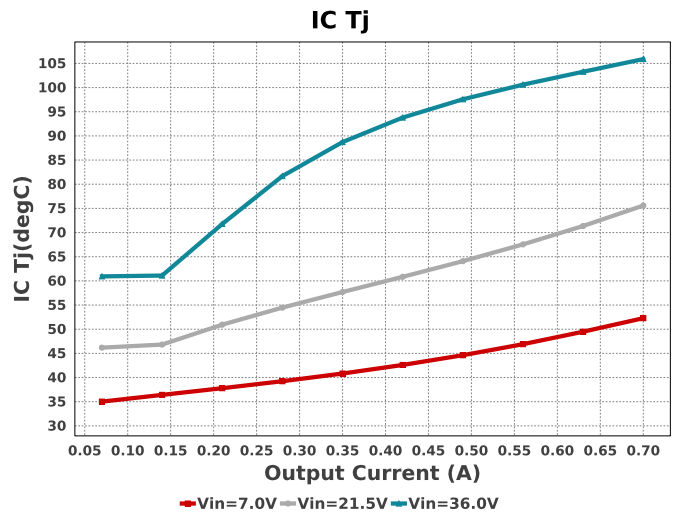
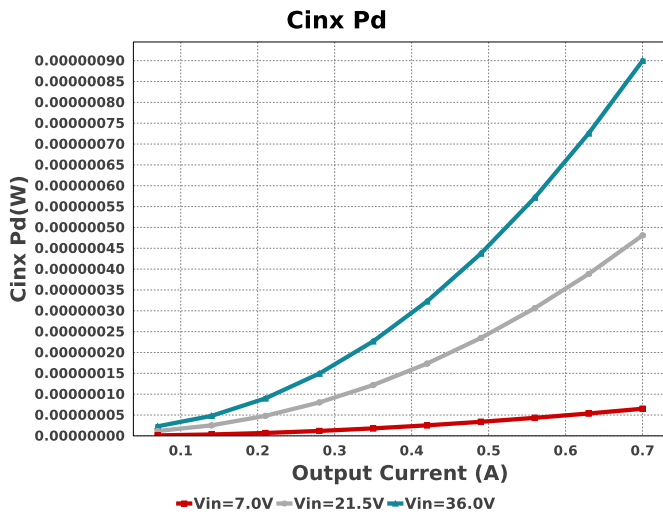
Design Alerts

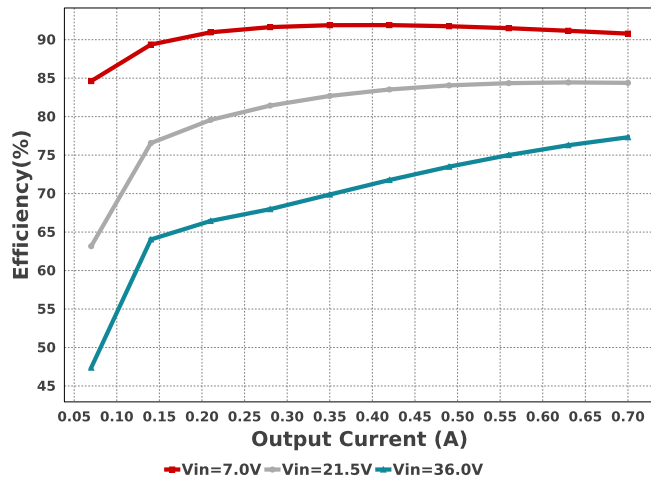
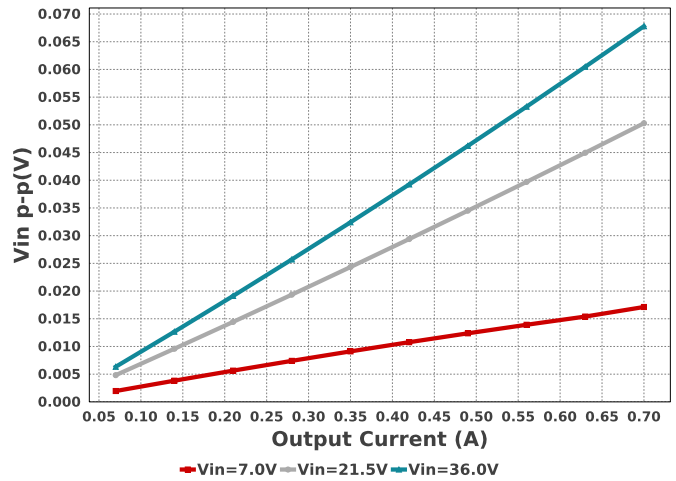
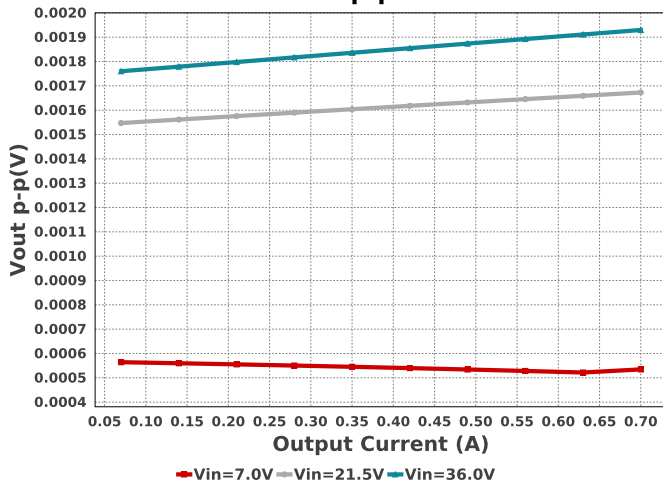
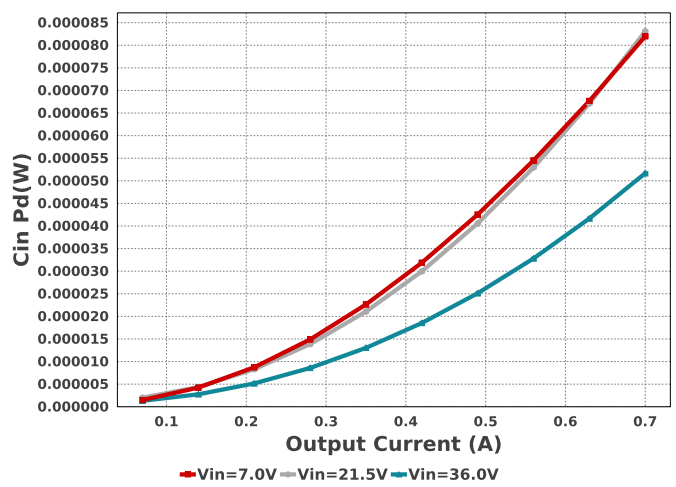
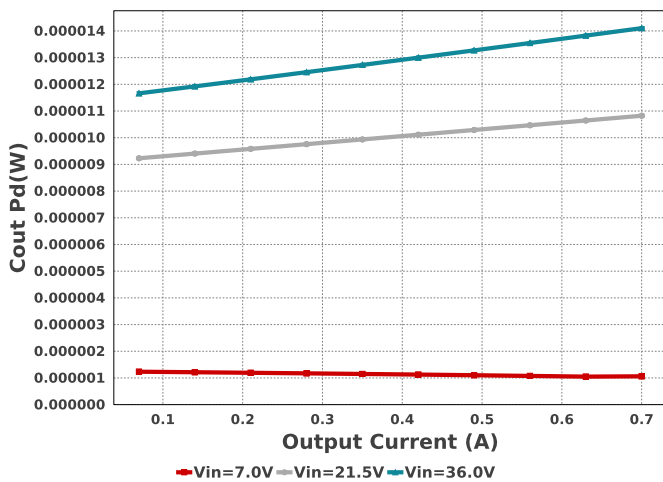
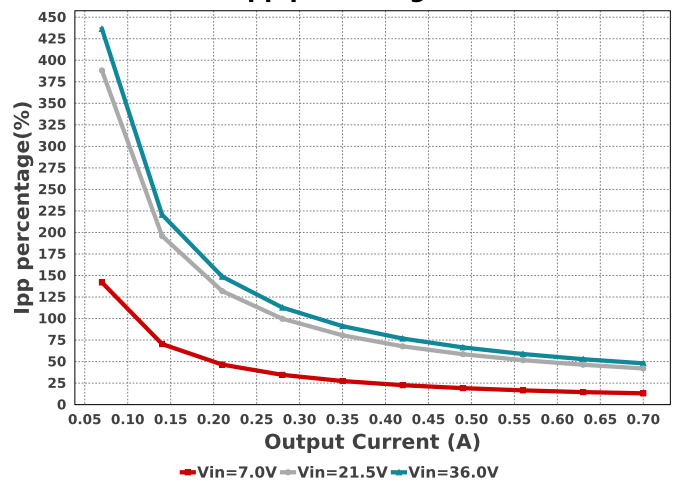
Component Selection Information

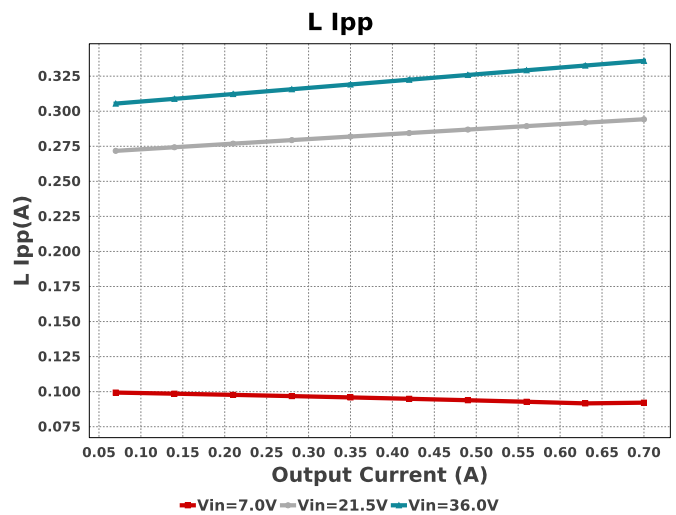
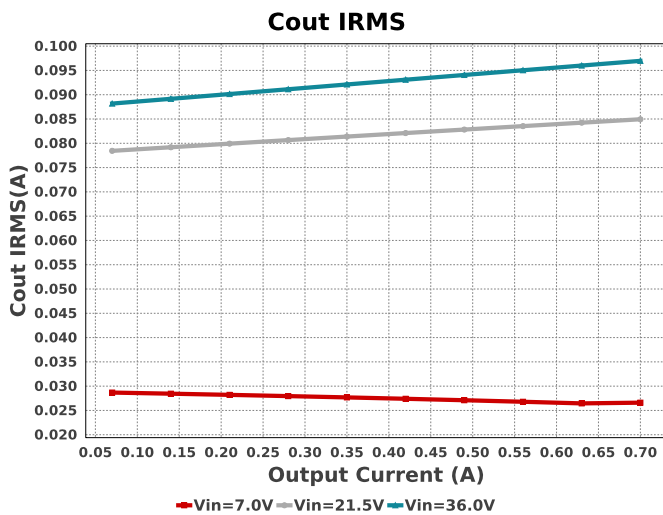
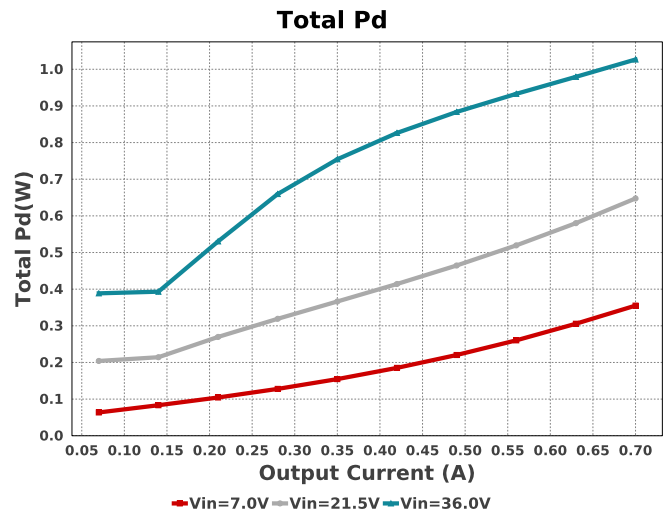
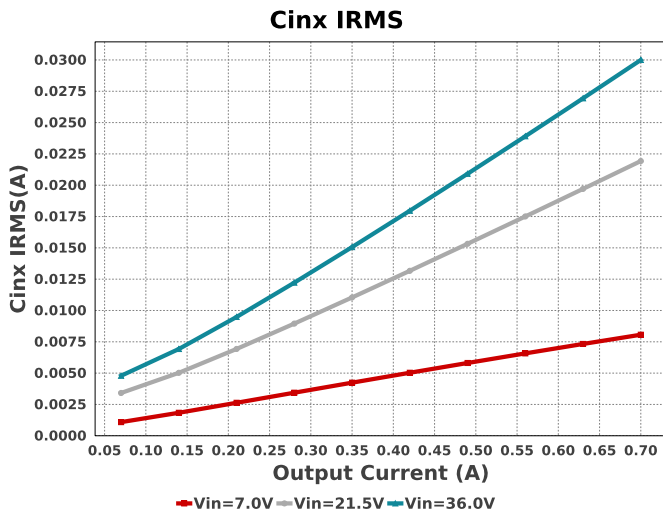
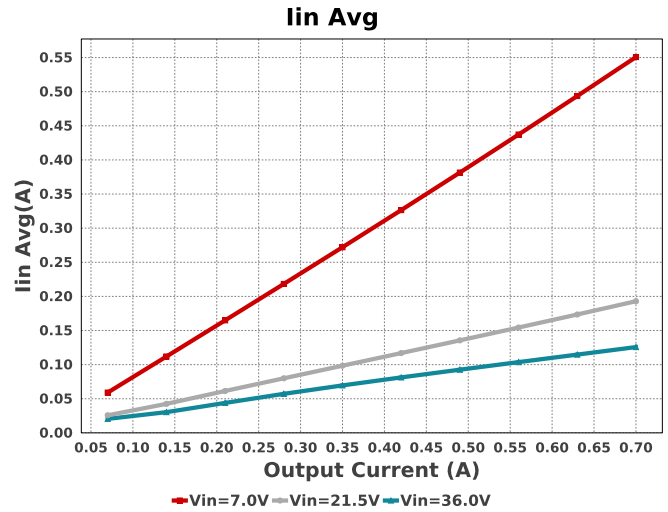
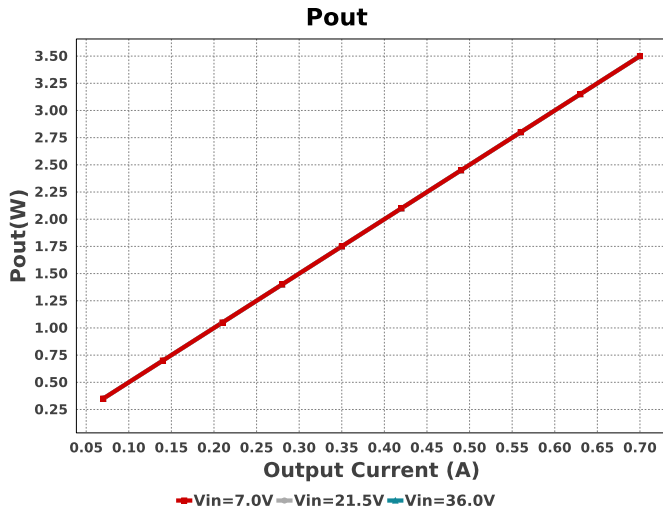
The LMR50410Y5F-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.

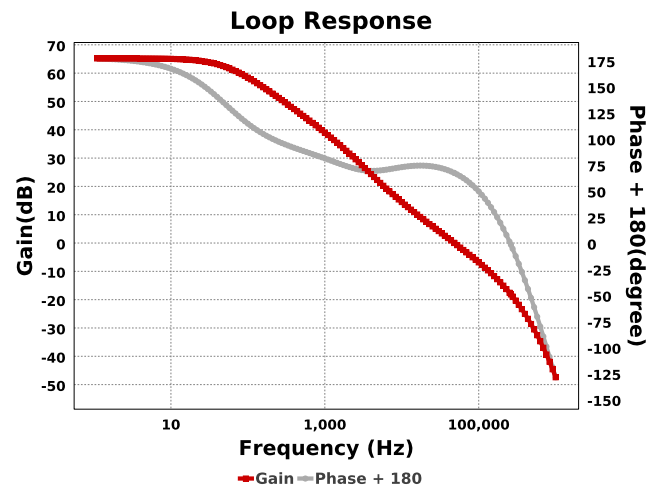
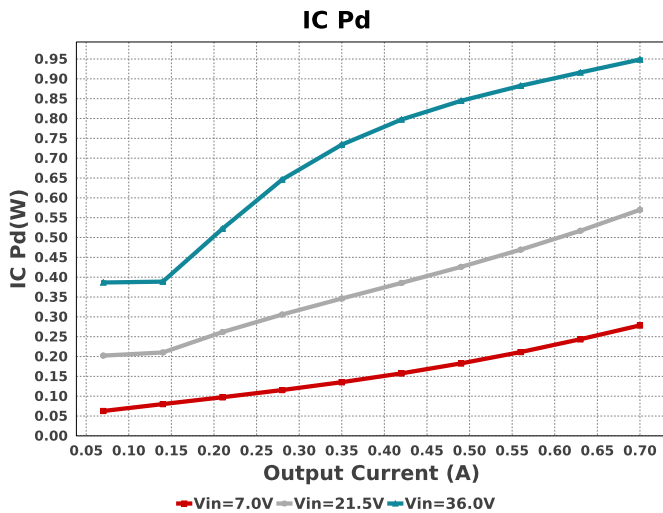
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	CUSTOM	CUSTOM Series= ?	Cap= 100.0 nF VDC= 16.0 V IRMS= 0.0 A	1	NA	CUSTOM 0 mm ²
Cin	TDK	C2012X5R1H475K125AB Series= X5R	Cap= 4.7 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 4.3 A	1	\$0.12	0805 7 mm ²
Cinx	MuRata	GRM21BR71H104KA01L Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 3.85 A	1	\$0.03	0805 7 mm ²
Cout	Kemet	C0805C106K8PACTU Series= X5R	Cap= 10.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 11.43 A	2	\$0.03	0805 7 mm ²
L1	Würth Elektronik	74405042068	L= 6.8 uH 156.0 mOhm	1	\$0.42	WE-LQSH_4020 24 mm ²
U1	Texas Instruments	LMR50410Y5FQDBVRQ1	Switcher	1	\$0.50	DBV0006A 15 mm ²



Efficiency**Vin p-p****Vout p-p****Cin Pd****Cout Pd****Ipp percentage**





Operating Values

#	Name	Value	Category	Description
1.	BOM Count	7		Total Design BOM count
2.	Total BOM	NA		Total BOM Cost
3.	Cin IRMS	227.327 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	51.678 μ W	Capacitor	Input capacitor power dissipation
5.	Cinx IRMS	29.999 mA	Capacitor	Bulk capacitor RMS ripple current
6.	Cinx Pd	899.91 nW	Capacitor	Bulk capacitor power dissipation
7.	Cout IRMS	96.968 mA	Capacitor	Output capacitor RMS ripple current
8.	Cout Pd	14.104 μ W	Capacitor	Output capacitor power dissipation
9.	IC IpK	867.953 mA	IC	Peak switch current in IC
10.	IC Pd	948.64 mW	IC	IC power dissipation
11.	IC Tj	105.891 degC	IC	IC junction temperature
12.	IC Tolerance	75.0 mV	IC	IC Feedback Tolerance
13.	ICThetaJA Effective	80.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
14.	Iin Avg	125.74 mA	IC	Average input current
15.	Ipp percentage	47.987 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
16.	L Ipp	335.907 mA	Inductor	Peak-to-peak inductor ripple current
17.	L Pd	77.907 mW	Inductor	Inductor power dissipation
18.	Cin Pd	51.678 μ W	Power	Input capacitor power dissipation
19.	Cinx Pd	899.91 nW	Power	Bulk capacitor power dissipation
20.	Cout Pd	14.104 μ W	Power	Output capacitor power dissipation
21.	IC Pd	948.64 mW	Power	IC power dissipation
22.	L Pd	77.907 mW	Power	Inductor power dissipation
23.	Total Pd	1.027 W	Power	Total Power Dissipation
24.	Cross Freq	48.264 kHz	System	Bode plot crossover frequency
25.	Duty Cycle	15.668 %	System Information	Duty cycle
26.	Efficiency	77.32 %	System Information	Steady state efficiency
27.	FootPrint	70.0 mm ²	System Information	Total Foot Print Area of BOM components
28.	Frequency	2.1 MHz	System Information	Switching frequency
29.	Gain Marg	-18.159 dB	System Information	Bode Plot Gain Margin
30.	Iout	700.0 mA	System Information	Iout operating point
31.	Low Freq Gain	65.191 dB	System Information	Gain at 1Hz
32.	Mode	CCM	System Information	Conduction Mode
33.	Phase Marg	68.892 deg	System Information	Bode Plot Phase Margin
34.	Pout	3.5 W	System Information	Total output power
35.	Vin	36.0 V	System Information	Vin operating point
36.	Vin p-p	67.8 mV	System Information	Peak-to-peak input voltage
37.	Vout	5.0 V	System Information	Operational Output Voltage

#	Name	Value	Category	Description
38.	Vout Tolerance	1.5 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
39.	Vout p-p	1.93 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	700.0 m	Maximum Output Current
VinMax	36.0	Maximum input voltage
VinMin	7.0	Minimum input voltage
VinTyp	14.0	Typical input voltage
Vout	5.0	Output Voltage
base_pn	LMR50410Y5F-Q1	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 7.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 9BEBB61A34925AAD[v1]
2. **LMR50410Y5F-Q1** Product Folder : <http://www.ti.com/product/LMR50410%2DQ1> : contains the data sheet and other resources.

Important Notice and Disclaimer

TI provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources AS IS and with all faults, and disclaims all warranties. These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Providing these resources does not expand or otherwise alter TI's applicable Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with TI products.